AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings of claims in the application:

LISTING OF CLAIMS:

- 1 7 (cancelled)
- 8. (new) A mold for making a composite material part, the mold being coated in a stripping composition comprising:
- · 100 parts by weight of a base ingredient constituted by an epoxy polydimethylsiloxane;
- · 0.5 to 10 parts by weight of a polymerization agent for polymerizing the base ingredient and constituted by a diaryliodonium salt;
- · an anti-adhesion modulator constituted by a silicone polymer, present at a concentration of not more than 30 parts by weight; and
- · an anti-stick agent making the composition less tacky prior to polymerization, constituted at least by a vinyl ether compound, which is present at a concentration of not more than 40 parts by weight.
- 9. (new) A mold according to claim 8, wherein said anti-adhesion modulator is also constituted by an epoxy polydimethylsiloxane.
- 10. (new) A mold according to claim 8, wherein said anti-stick agent is constituted by a mixture of a monovinyl ether and a divinyl ether.
- 11. (new) A mold according to claim 10 wherein said monovinyl ether is dodecyl monovinyl ether.
- 12. (new) A mold according to claim 10, wherein said divinyl ether is 1.4 cyclohexane dimethanol divinyl ether.

- 13. (new) A mold according to claim 8, wherein said stripping composition has:
 - · 5 to 7 parts by weight of the polymerization agent;
- \cdot 5 to 10 parts by weight of the anti-adhesion modulator, said anti-adhesion modulator being an epoxy polydimethylsiloxane; and
- the anti-stick agent being present at a concentration in the range 8 to 12 parts by weight of a dodecyl monovinyl ether and 8 to 12 parts by weight of a cyclohexane dimethanol divinyl ether.
- 14. (new) A mold according to claim 13, wherein the stripping composition has:
 - · 6 parts by weight of the polymerization agent;
 - · 8 parts by weight of the anti-adhesion modulator; and
- the anti-stick agent being present at a concentration of 11.4 parts by weight of a dodecyl monovinyl ether and 11.4 parts by weight of a cyclohexane dimethanol divinyl ether.
- 15. (new) A wipe or cloth impregnated in a stripping composition presenting the characteristics of claim 8.
- 16. (new) A method of molding a composite material part, wherein the mold is coated in a stripping composition comprising:
- 100 parts by weight of a base ingredient constituted by an epoxy polydimethylsiloxane;
- \cdot 0.5 to 10 parts by weight of a polymerization agent for polymerizing the base ingredient and constituted by a diaryliodonium salt;
- \cdot an anti-adhesion modulator constituted by a silicone polymer, present at a concentration of not more than 30 parts by weight; and
- · an anti-stick agent making the composition less tacky prior to polymerization, constituted at least by a vinyl ether compound, which is present at a concentration of not more than 40 parts by weight.

- 17. (new) A method according to claim 16, wherein said antiadhesion modulator is also constituted by an epoxy polydimethylsiloxane.
- 18. (new) A method according to claim 16, wherein said anti-stick agent is constituted by a mixture of a monovinyl ether and a divinyl ether.
- 19. (new) A method according to claim 18, wherein said monovinyl ether is dodecyl monovinyl ether.
- 20. (new) A method according to claim 18, wherein said divinyl ether is 1.4 cyclohexane dimethanol divinyl ether.
- 21. (new) A method according to claim 16, wherein said stripping composition has:
 - · 5 to 7 parts by weight of the polymerization agent;
- \cdot 5 to 10 parts by weight of the anti-adhesion modulator, said anti-adhesion modulator being an epoxy polydimethylsiloxane; and
- \cdot the anti-stick agent being present at a concentration in the range 8 to 12 parts by weight of a dodecyl monovinyl ether and 8 to 12 parts by weight of a cyclohexane dimethanol divinyl ether.
- 22. (new) A method according to claim 21, wherein said stripping composition has:
 - · 6 parts by weight of the polymerization agent;
 - · 8 parts by weight of the anti-adhesion modulator; and
- the anti-stick agent being present at a concentration of 11.4 parts by weight of a dodecyl monovinyl ether and 11.4 parts by weight of a cyclohexane dimethanol divinyl ether.
- 23. (new) A method according to claim 16, wherein the surface of the mold is coated with the stripping composition to a thickness of micrometer order.

- 24. (new) A method according to claim 16, wherein the surface of the mold is coated with a wipe or a cloth impregnated in the stripping composition.
- 25. (new) A method according to claim 16, wherein the stripping composition is polymerized under the action of ultraviolet radiation.
- 26. (new) A method according to claim16, wherein the stripping composition is polymerized by applying heat.
- 27. (new) A method according to claim 26, wherein the polymerization cycle is 1 hour at $150^{\circ}\text{C} \pm 5^{\circ}\text{C}$.
- 28. (new) A method according to claim 26, wherein the polymerization cycle is 30 minutes at 100°C.
- 29. (new) A method according to claim 21, wherein the surface of the mold is coated with a wipe or a cloth impregnated in the stripping composition.
- 30. (new) A method according to claim 29, wherein the stripping composition is polymerized by applying heat.
- 31. (new) A method according to claim 16, in which the composite material part is a helicopter blade or an element of such a blade.